


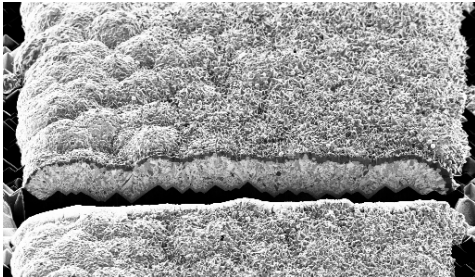
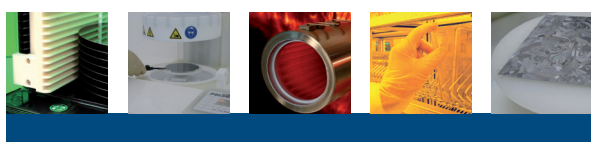


■ Electroplating solutions

NBT has designed specialised electroplating solutions based on many years of engineering experience and application expertise for MEMS, semiconductor industries, PCBs and photovoltaic technologies.



Product	Application	Features
MEMS/Semiconductors		
NB Semiplate Au 100	Surface finishing Bond pads	Very stable bath, sulfite based very uniform thickness, shiny surface, low temperature plating
NB Semiplate Cu 100	Conducting lines Sacrificial layers	Sulfuric acid based, shiny surface, uniform thickness, low stress
NB Semiplate Sn 100	Soldering	MSA based, good bonding
NB Semiplate Ni 100	Mechanical elements	High purity bath and deposit, medium temperature plating, low stress, controlled mechanical properties
Photovoltaics		
sun-Ag 100	Surface finish for bonding	Cyanide-free Ag
sun-Tin 100	Surface finish for bonding	Good uniformity and bonding
sun-Cu 100	Conducting lines	High-speed process, low stress
sun-Ni 100	Barrier layer	good adhesion, low stress
sun-NiSi	Porous Si etching and Ni plating from one solution	Ethanol-free, low HF concentration plates Ni in nm-pores excellent adhesion



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